

Material Declaration Report

Package Type:	QSOP 16L
Pericom Package Code:	Q16(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A
REACH Compliance:	Yes
Halogen Free:	Yes

Component Weight (mg):	77.500
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	4/30/2010

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	42.610	UTL and SPEL	Silica Fused	60676-86-0	88.000	37.496
			Epoxy Resin	Proprietary	5.000	2.130
			Phenolic Resin	Proprietary	4.500	1.917
			Epoxy, Cresol Novolac	29690-82-2	2.000	0.852
			Carbon Black	1333-86-4	0.500	0.213
LEADFRAME	30.060		Copper	7440-50-8	97.021	29.164
			Iron	7439-89-6	2.350	0.706
			Silver	7440-22-4	0.453	0.136
			Zinc	7440-66-6	0.111	0.033
			Phosphorus	7723-14-0	0.065	0.020
SILICON DIE	1.680		Silicon (Si)	7440-21-3	99.192	1.666
			Non-hazardous Metal	Proprietary	0.808	0.014
DIE ATTACH EPOXY	0.334	UTL	Silver	7440-22-4	80.000	0.267
			Functionalized Urethane	72869-86-4	8.000	0.027
			Diester Resin	94-80-4	7.000	0.023
			Epoxy Resin	Proprietary	5.000	0.017
		SPEL	Silver	7440-22-4	80.000	0.267
			Epoxy Resin	9003-36-5	10.000	0.033
			Diluent	26447-14-3	6.000	0.020
			Hardener	620-92-8	3.500	0.012
Dicyandamide	461-58-5	0.500	0.002			
GOLD WIRE	0.267		Gold(Au)	7440-57-5	99.990	0.267
			Impurities	-	0.010	0.000
SOLDER PLATING	2.550		Tin (Sn)	7440-31-5	99.990	2.550
			Impurities	-	0.010	0.000

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	<p>Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium</p> <table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O	O
	Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm														
O	O	O	O	O	O														
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>																			